

5-104186-1 ✓ ACTIVE

AMPMODU | AMPMODU System 50

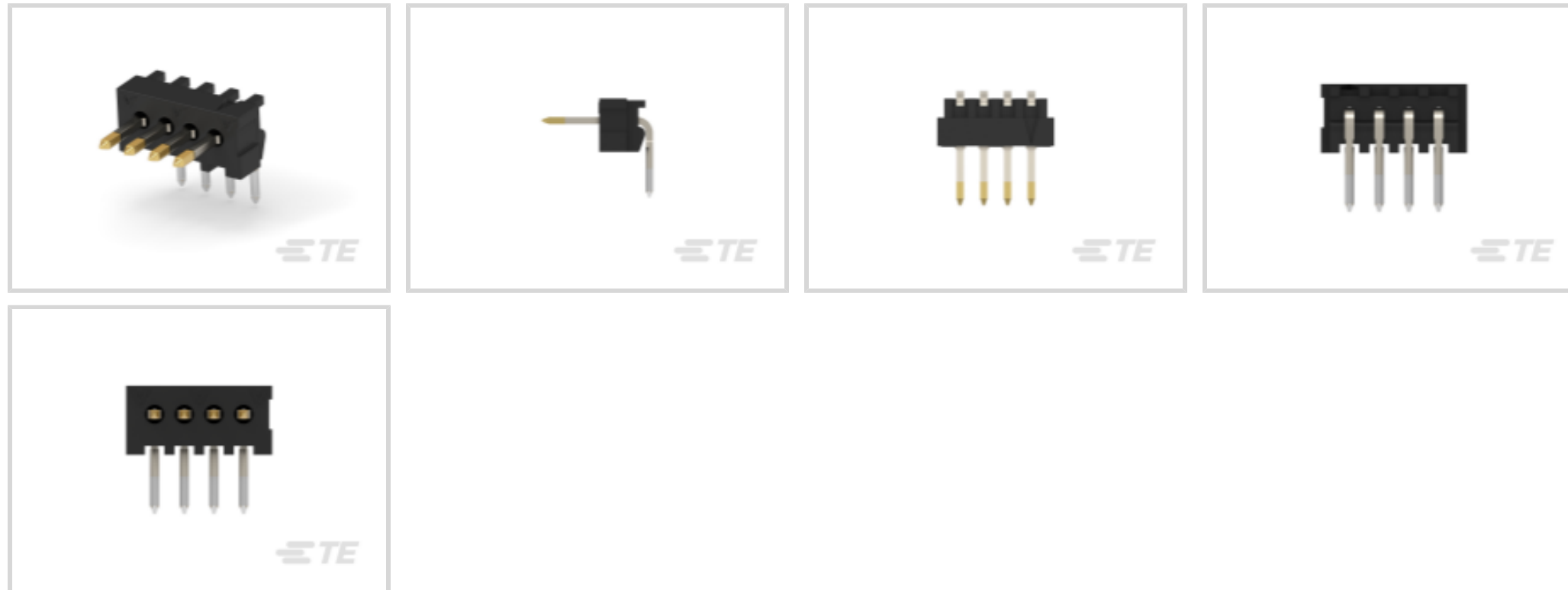
TE Internal #: 5-104186-1

PCB Mount Header, Right Angle, Board-to-Board, 4 Position, 1.27 mm [.05 in] Centerline, Unshrouded, Gold, Through Hole - Solder, AMPMODU System 50

[View on TE.com >](#)



Connectors > PCB Connectors > PCB Headers & Receptacles



EU RoHS Compliance: **Compliant**

EU ELV Compliance: **Compliant**

PCB Connector Assembly Type: **PCB Mount Header**

PCB Mount Orientation: **Right Angle**

Connector System: **Board-to-Board**

Features

Other

EU RoHS Compliance	Compliant
EU ELV Compliance	Compliant
Position Locations Omitted	0

Product Type Features

PCB Connector Assembly Type	PCB Mount Header
Connector System	Board-to-Board
Header Type	Unshrouded
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board

Configuration Features

Connector Contact Load Condition	Fully Loaded
Board-to-Board Configuration	Perpendicular
PCB Mount Orientation	Right Angle
Number of Positions	4



Number of Rows	1
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Electrical Characteristics

Operating Voltage	30 VAC
Insulation Resistance	5000 MΩ
Dielectric Withstanding Voltage (Max)	500 VAC

Body Features

Primary Product Color	Black
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Contact Features

Contact Underplating Material	Nickel
PCB Contact Termination Area Plating Material Finish	Matte
Contact Mating Area Plating Material Thickness	.76 μm[30 μin]
Mating Square Post Dimension	.38 mm[.015 in]
Contact Shape & Form	Rectangular
PCB Contact Termination Area Plating Material Thickness	3.81 – 6.35 μm[150 – 250 μin]
Contact Base Material	Copper Alloy
PCB Contact Termination Area Plating Material	Tin
Contact Mating Area Plating Material	Gold
Contact Type	Pin
Contact Current Rating (Max)	3.6 A

Termination Features

Termination Post & Tail Diameter	.38 mm[.015 in]
Termination Post & Tail Length	2.54 mm[.1 in]
Termination Method to PCB	Through Hole - Solder

Mechanical Attachment

PCB Mount Retention	Without
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Mating Alignment	Without

Housing Features

Housing Material	LCP
Centerline (Pitch)	1.27 mm[.05 in]

Dimensions



PCB Thickness (Recommended)	1.57 mm[.062 in]
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Usage Conditions

Housing Temperature Rating	High
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]

Operation/Application

Solder Process Feature	Board Standoff
Circuit Application	Signal

Industry Standards

Compatible With Agency/Standards Products	UL, CSA
UL Rating	Recognized
Compatible With Approved Standards Products	UL E28476, CSA LR7189
UL Flammability Rating	UL 94V-0

Packaging Features

Packaging Quantity	85
Packaging Method	Tube, Box

Product Compliance

[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Wave solder capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part



numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

Compatible Parts

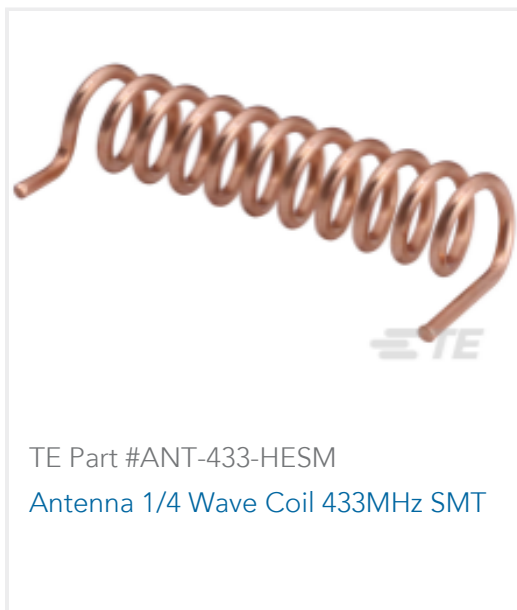


Also in the Series | AMPMODU System 50



Customers Also Bought





Documents

Product Drawings

[04 SYS 50 HDR SRRA UNSHRD TIN](#)

English

CAD Files

[3D PDF](#)

3D

Customer View Model

[ENG_CVM_CVM_5-104186-1_W.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_5-104186-1_W.3d_igs.zip](#)

English

Customer View Model

[ENG_CVM_CVM_5-104186-1_W.3d_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

[AMPMODU_INTERCONNECTION_SYSTEM_SECTION3AND4](#)

English

[AMPMODU SYSTEM 50 QUICK REFERENCE GUIDE](#)

English

[AMPMODU SYSTEM 50](#)

English

Product Specifications

[Application Specification](#)

English